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6-18-2
Robertson
Arndt

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Colleen J. Dew

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 2841

<u>In re application of</u>	:	June 13, 2002
Hormazdyar H. Dalal et al.	:	Examiner: David A. Foster
Serial No. : 09/158,616	:	
Filed: September 22, 1998	:	IBM Corporation
Title: A MULTI-LEVEL ELECTRONIC	:	Dept. 18G/Bldg, 300-482
PACKAGE AND METHOD FOR	:	2070 Route 52
MAKING SAME	:	Hopewell Junction, NY
	:	12533-6531

Amendment

Commissioner for Patents and Trademarks
Washington, D.C. 20231

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JUN 13 2002

TECHNOLOGY CENTER 2800

Sir:

Kindly amend the claims as follows:

- D1
- 1 1. (thrice amended) A package for containing electronic components, the
 - 2 package comprising:
 - 3 a first circuitized card;
 - 4 a second circuitized card;
 - 5 an interposer interposed between the first and second circuitized cards,
 - 6 the interposer having an opening, the opening in the interposer and the first and
 - 7 second circuitized card forming a cavity for containing at least one electronic
 - 8 component
 - 9 wherein the first circuitized card has a bottom surface and there is at least one
 - 10 component mounted to the bottom surface, and wherein the interposer, first
 - 11 circuitized card, and second circuitized card are circuitized multi-layer organic
 - 12 laminate cards.